

Patent Abstracts of Japan

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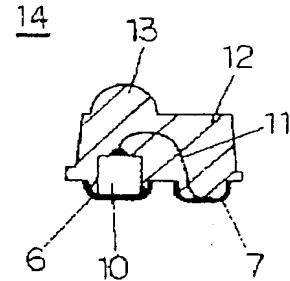
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TITLE : MANUFACTURE OF ELECTRONIC
COMPONENT WITH BUMP



ABSTRACT : PROBLEM TO BE SOLVED: To provide a method for manufacturing an electronic component by which electronic components can be manufactured easily at low cost with high yield.

SOLUTION: Recessed sections are formed on a base material by etching, and then electrodes 6, 7 are formed on the surfaces of the recessed sections by plating. Then, a chip 10 is mounted on the electrode 6 and a pad of the chip 10 and the electrode 7 are connected by a wire 11. After the chip 10 and the wire 1 have been sealed with resin into a molded body 12, the base material is removed to expose the electrodes 6, 7, which become bumps. Next, thin sections connecting the molded bodies 12 are cut so as to obtain separate electronic component 14 with bumps.

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